

Features

- 8-Channel Smart Low-side Driver Array
 - 40-V Max Operating Voltage, 48-V Abs Max Voltage
 - 500-mΩ Low- $R_{DS(ON)}$ with Maximum 1.5-A Driver Capability
 - Integrated Free-wheeling Diodes for Inductive Loads
 - Parallel Channel Driving Capability
- 10-MHz High-speed 16-bit Shift Register Interface
 - Input Noise Filtering with Daisy-chain Communication
- Diagnostics and Protection
 - Power On Reset
 - Over-Current Protection
 - Short-Circuit Protection
 - Over-Temperature Protection
 - Open-drain Fault Alarm

Description

The TPM8860 provides an 8-ch low-side driver with channel-independent protection and diagnostics. It has a low $R_{DS(ON)}$ MOSFET array with free-wheeling diodes to support all kinds of loads, resistive, inductive, and capacitive. It supports a single high-voltage supply.

It supports a high-speed shift register interface with daisy-chain individually controlling each channel. Over-current protection, short-circuit, and open-circuit allow the controller to protect the system from faulty loads. Open-drain fault output allows the controller to respond to fault scenario with interrupt input.

Multiple devices can be connected in a daisy-chain configuration to save MCU I/Os. The device also provides undervoltage lockout and over-temperature shutdown protection.

Applications

- Relays, Solenoids, Unipolar Stepper Motors
- Electric Expansion Valves, Linear Valves
- LEDs and Heaters
- PLC Digital Outputs
- Electromagnetic Loads

Typical Application Circuit

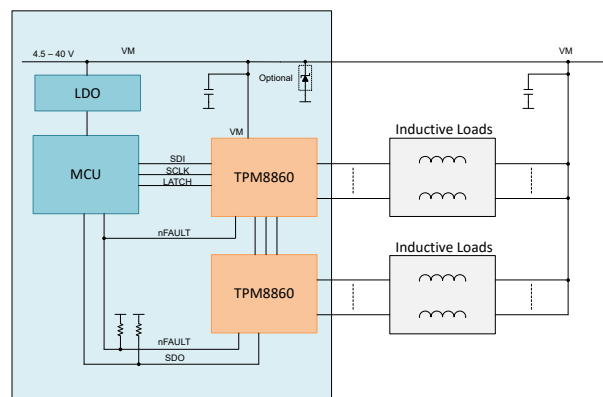


Table of Contents

Features	1
Applications	1
Description	1
Typical Application Circuit	1
Revision History	3
Pin Configuration and Functions	4
Specifications	5
Absolute Maximum Ratings ⁽¹⁾	5
ESD, Electrostatic Discharge Protection.....	5
Recommended Operating Conditions.....	6
Thermal Information.....	6
Electrical Characteristics.....	7
Typical Performance Characteristics.....	9
Detailed Description	11
Overview.....	11
Functional Block Diagram.....	11
Feature Description.....	12
Application and Implementation	15
Application Information	15
Typical Application.....	17
Layout	18
Layout Guideline.....	18
Layout Example.....	18
Tape and Reel Information	19
Package Outline Dimensions	20
ETSSOP-16-D.....	20
Order Information	21
IMPORTANT NOTICE AND DISCLAIMER	22

Revision History

Date	Revision	Notes
2024-04-12	Rev.A.0	Initial release

Pin Configuration and Functions

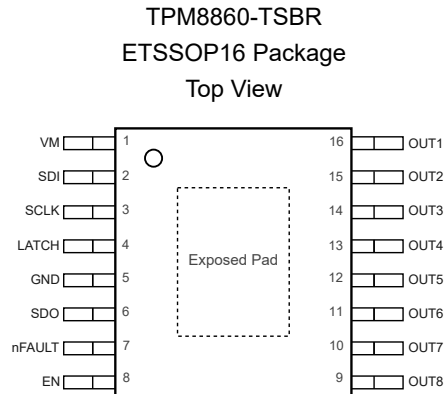


Table 1. Pin Functions: TPM8860-TSBR

Pin	Name	I/O	Description
1	VM	P	Motor power supply, connect to 10- μ F capacitor with 0.1- μ F close to VM pin
2	SDI	I	Serial interface data input
3	SCLK	I	Serial interface clock input
4	LATCH	I	Serial interface latch input
5	GND	G	Device ground
6	SDO	O	Serial interface data output, push-pull output
7	nFAULT	OD	Open-drain fault output
8	EN	I	Output enable. Logic high to enable all outputs, logic low to disable all outputs.
9	OUT8	O	Output channel 8
10	OUT7	O	Output channel 7
11	OUT6	O	Output channel 6
12	OUT5	O	Output channel 5
13	OUT4	O	Output channel 4
14	OUT3	O	Output channel 3
15	OUT2	O	Output channel 2
16	OUT1	O	Output channel 1

Specifications

Absolute Maximum Ratings ⁽¹⁾

Parameter		Min	Max	Max
VM	Power Supply Voltage	-0.3	48	V
	Power Supply Voltage (100-ns Pulse)	-0.3	50	V
EN, LATCH, SCLK, SDI	Input Voltage	-0.3	7	V
SDO, nFAULT	Output Voltage	-0.3	7	V
V _{OUTX}	Power Output Voltage	-0.3	48	V
	Power Output Voltage (100-ns Pulse)	-0.3	50	V
T _J	Maximum Junction Temperature		150	°C
T _A	Operating Temperature Range	-40	125	°C
T _{STG}	Storage Temperature Range	-65	150	°C
T _L	Lead Temperature (Soldering 10 sec)		260	°C

(1) Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. Exposure to any Absolute Maximum Rating condition for extended periods may affect device reliability and lifetime.

ESD, Electrostatic Discharge Protection

Symbol	Parameter	Condition	Minimum Level	Unit
HBM	Human Body Model ESD	ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	4	kV
CDM	Charged Device Model ESD	ANSI/ESDA/JEDEC JS-002 ⁽²⁾	1	kV

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

(2) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

Recommended Operating Conditions

Parameter		Min	Max	Unit
VM	Power Supply Voltage	5	40	V
EN, SDI, SCLK, LATCH	Logic Input Voltage	0	5.5	V
SDO, nFAULT	Open Drain Output Voltage	0	5.5	V
V _{OUTx}	Output Voltage	0	40	V
I _{OUTx}	Continuous Output Current		1.5	A
	Peak Output Current		2	A
I _{VM}	Reverse Current		4	A
I _{GND}	Ground Current		4	A
T _J	Maximum Junction Temperature		150	°C
T _A	Operating Temperature Range	-40	125	°C

Thermal Information

Package Type	θ_{JA}	θ_{JC}	Unit
ETSSOP16	62.8	52.6	°C/W

Electrical Characteristics

 All test conditions: $V_M = 12\text{ V}$, $T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$, unless otherwise noted.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Power Supply						
I_{VM}	VM Operating Supply Current	$V_M = 24\text{ V}$		1	4	mA
V_{UVLO_rising}	VM Under-voltage-lock-out Rising Edge	VM rising edge			4.4	V
$V_{UVLO_falling}$	VM Under-voltage-lock-out Falling Edge	VM falling edge			4.4	V
Logic Inputs / Outputs (EN, LATCH, SDI, SCLK, nFAULT, SDO)						
V_{IL}	Input Low Voltage Threshold		0.7		1.3	V
V_{IH}	Input High Voltage Threshold		1		1.5	V
I_{IL}	Input Low Current	$V_{IN} = 0\text{ V}$	-20		20	μA
I_{IH}	Input High Current	$V_{IN} = 3.3\text{ V}$			100	μA
R_{PD}	Input Pull-down Resistance		60	100	130	k Ω
V_{OL}	Output Low Voltage	$I_O = 5\text{ mA}$			0.5	V
$I_{OH(nFAULT)}$	nFAULT Output High Leakage Current	$V_O = 3.3\text{ V}$	-1		1	μA
R_{PU}	SDO Pull-up Resistance	Pull up to internal regulator		1.4		k Ω
V_{SDO_H}	Output High Voltage	$I_O = 0.1\text{ mA}$, $V_M = 5\text{ V} - 40\text{ V}$, steady state	2.5	4.5	5.9	V
I_{SDO_SRC}	SDO Source Current	$V_M = 24\text{ V}$, $V_{SDO} = V_{SDO_H} - 0.5\text{V}$		10		mA
I_{SDO_SINK}	SDO Sink Current	$V_M = 24\text{ V}$, $V_{SDO} = 0.3\text{ V}$		50	250	mA
Outputs						
$R_{ds(ON)}$	Output Low-side MOSFET on-resistance	$V_M = 24\text{ V}$, $I_O = 500\text{ mA}$, $T_J = 25^\circ\text{C}$		0.5		Ω
$R_{ds(ON)}$	Output Low-side MOSFET on-resistance	$V_M = 24\text{ V}$, $I_O = 500\text{ mA}$, $T_J = 150^\circ\text{C}$		0.8	1.2	Ω
I_{OPEN_OFF}	Open Load Detection Current during off State			30	50	μA
V_F	High-side Diode Forward Voltage	$V_M = 24\text{ V}$, $I_{SINK} = 500\text{ mA}$, $T_J = 25^\circ\text{C}$		0.9		V
I_{HSD_lkg}	High-side Diode Leakage Current	$V_M = 24\text{ V}$, $T_J = 25^\circ\text{C}$	-50		50	μA
$t_{OUT_risetime}$	Output Rise time	$V_M = 24\text{ V}$, $T_J = 25^\circ\text{C}$, Resistive load		90		ns
$t_{OUT_falltime}$	Output Fall time	$V_M = 24\text{ V}$, $T_J = 25^\circ\text{C}$, Resistive load		90		ns
Diagnostics and Protection						

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_{(OCP_TH)}$	Over-current Protection Threshold		1.65		2.8	A
$t_{(OCP_deg)}$	Over-current Protection Deglitch Time			3.5		μs
$V_{(OL_TH)}$	Open Load Detection Threshold			1.2		V
$t_{(OL_deg)}$	Open Load Detection Deglitch Time		7		17	μs
$I_{(OL_off)}$	Off-time Open-Load Source Current			30	50	μA
t_{TSD}	Thermal Shutdown Threshold		150	175		$^{\circ}C$
t_{TSD_HYS}	Thermal Shutdown Threshold Hysteresis			15		$^{\circ}C$

Typical Performance Characteristics

All test conditions: $V_{IN} = 12\text{ V}$, $T_A = +25^\circ\text{C}$, unless otherwise noted.

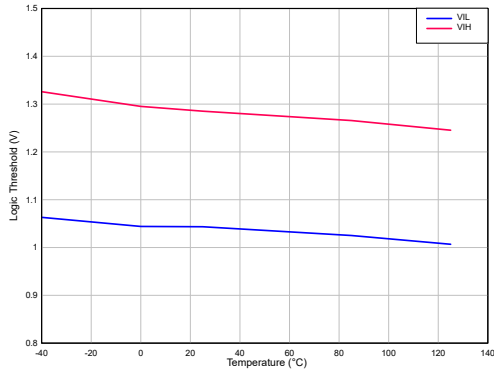


Figure 1. Logic Input Threshold vs. Temperature

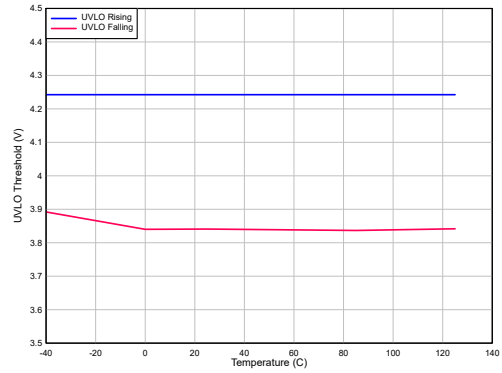


Figure 2. UVLO Threshold vs. Temperature

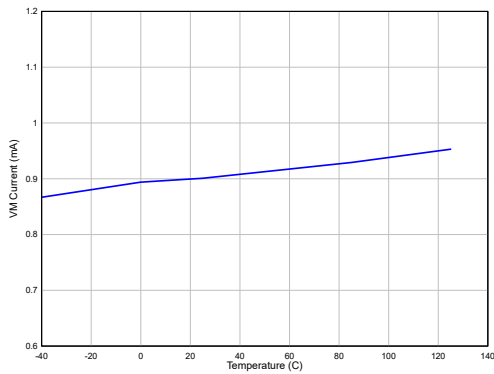


Figure 3. Quiescent Current vs. Temperature

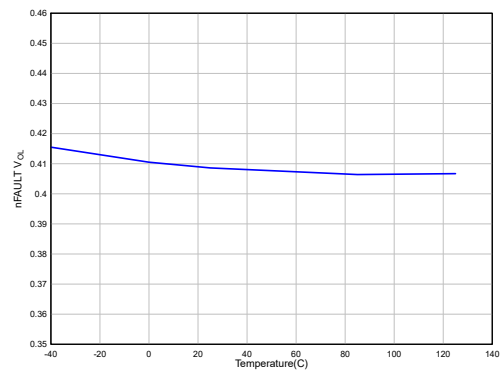


Figure 4. nFAULT V_{OL} vs. Temperature

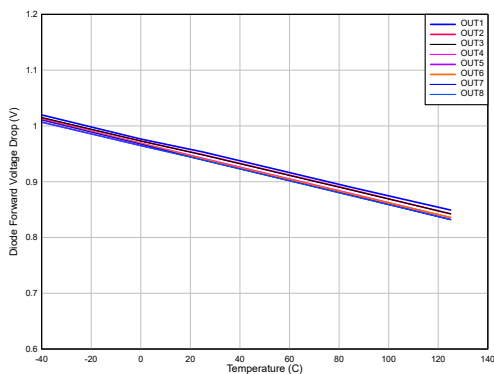


Figure 5. Forward Diode Drop vs. Temperature

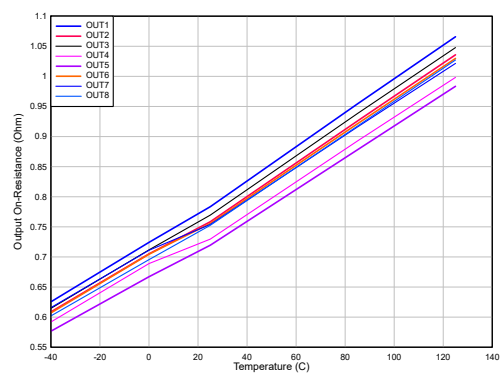


Figure 6. On-resistance vs. Temperature

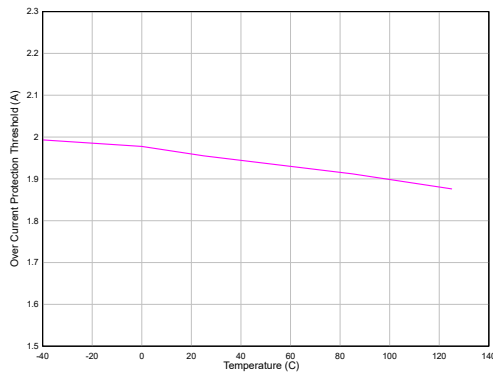


Figure 7. Over Current Protection Threshold vs. Temperature

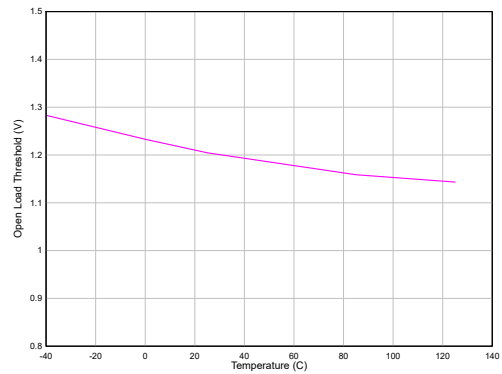


Figure 8. Open-Load Protection Threshold vs. Temperature

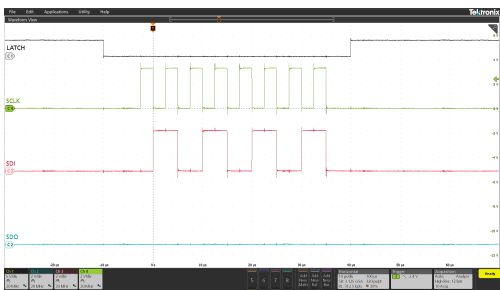


Figure 9. Serial Interface Write

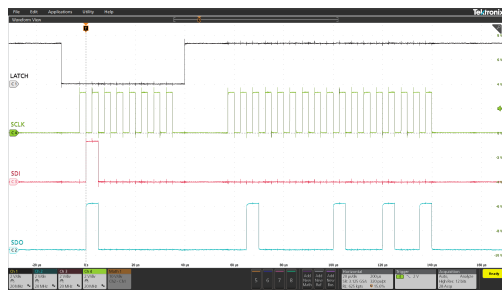


Figure 10. Serial Interface Read

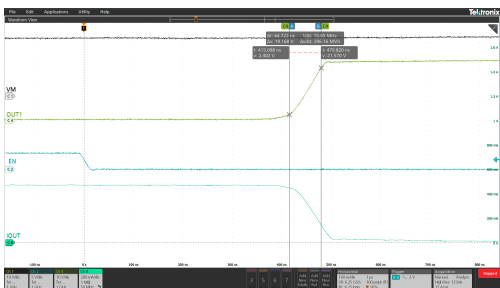


Figure 11. Output Rising Edge

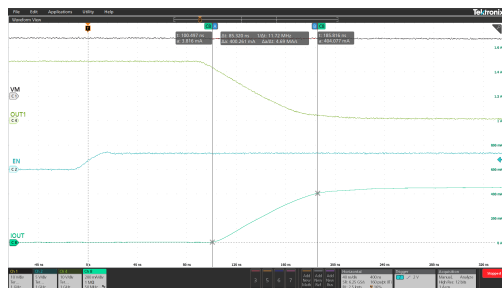


Figure 12. Output Falling Edge

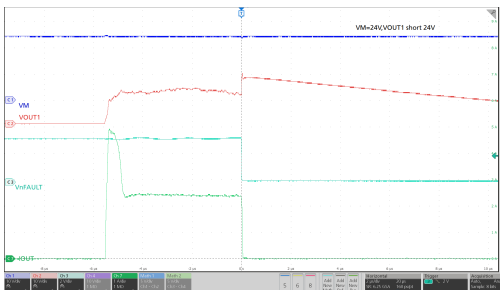


Figure 13. Short Circuit Protection

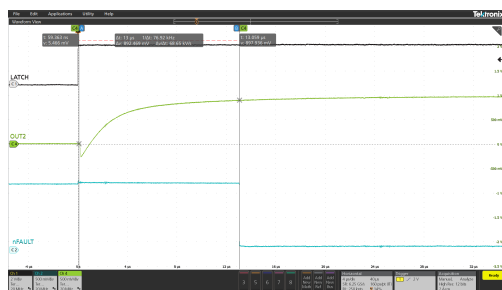


Figure 14. Open-Load Protection

Detailed Description

Overview

The TPM8860 is a smart high-voltage high-current low-side driver array with full diagnostics and protection. The device supports a maximum 40-V separated supply and driver voltage. 8-Ch low-side driver can be controlled individually via the serial interface. Each output channel has an integrated free-wheeling diode path for inductive loads such as solenoids, motors, electric expansion valves, and relays. The device has protection features including supply undervoltage monitoring, over-current protection, load open-circuit and short-circuit diagnostics, and over-temperature protection. Open-drain fault bus allows hardware interrupt for MCU to handle fault scenarios easily.

The device supports the daisy-chain connection of multiple devices together as well as an isolated interface with 3PEAK digital isolators.

Functional Block Diagram

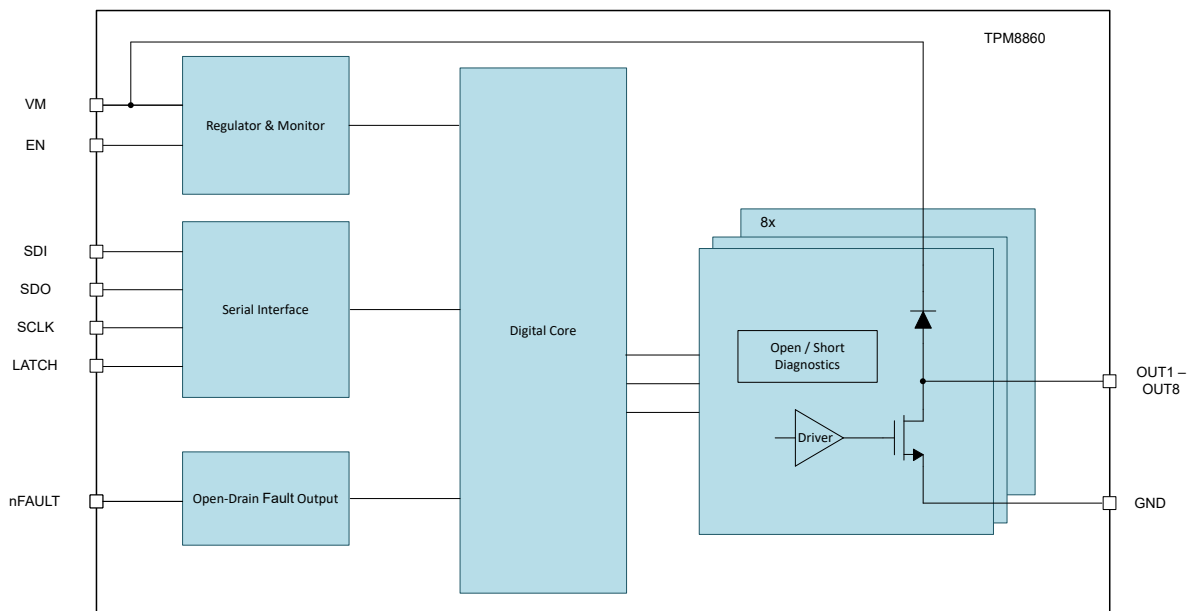


Figure 15. Functional Block Diagram

Feature Description

Supply and Reference

The TPM8860 supports single voltage rail VM. VM includes an undervoltage lockout (UVLO) monitor to prevent issues at low supply voltages. It is recommended to use 10- μ F capacitors on each rail to suppress voltage transients when driving inductive loads. When inductive loads may surge higher than 40-V, 3PEAK recommends to use TVS to suppress transient voltage.

The device has an EN input with an internal pull-down. When EN is low, the device is in a reset state, clearing the register maps and tri-stating the SDO pin. When EN is high, the device is in normal operation and can communicate via the serial interface.

Output Enable

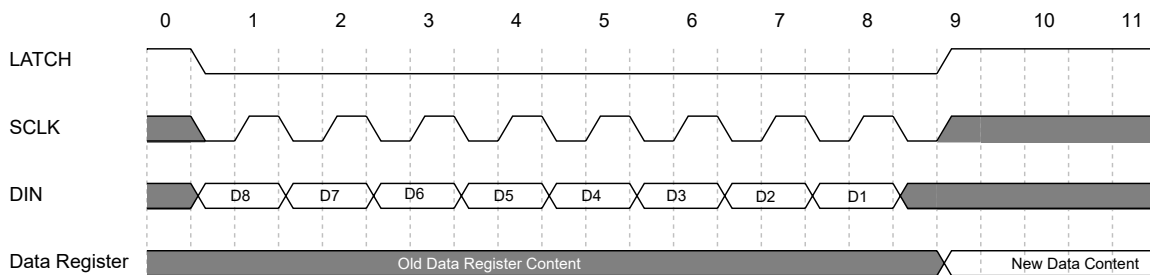
The TPM8860 provides an active high output enable, EN, to control the device outputs. When EN is low, the outputs are disabled with the register map cleared; When EN is high, the outputs are enabled. It has an internal pull-down resistor and can be left unconnected or connected to the ground for desired functionality.

Serial Communication

Serial Interface

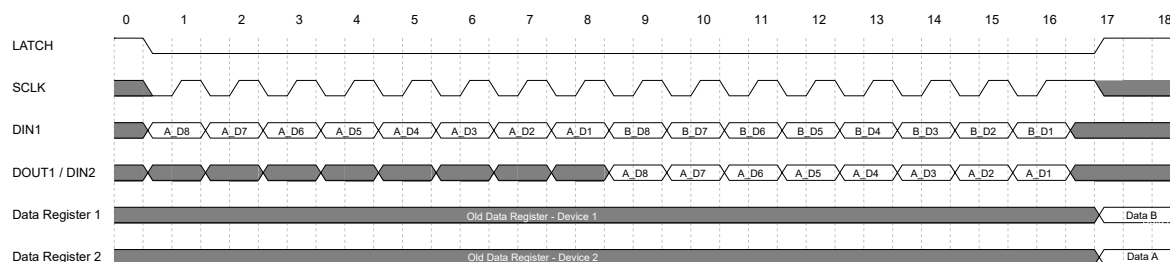
The TPM8860 device supports a high-speed shift-register serial interface with daisy-chain capability. The Serial Data Output (SDO) pin is configured as a push-pull output, connected to the internal 3.3-V voltage rail to enable high-speed communication.

During a write operation, when the device selection LATCH is low, on each rising edge of the serial clock (SCLK), the device shifts the Serial Data Input (SDI) into the internal shift register and updates the Serial Data Output (SDO) with the last bit of the shift register.



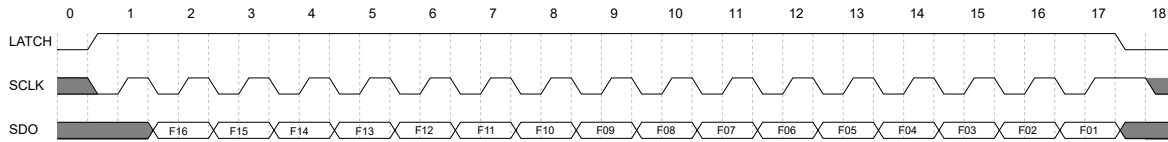
D8	D7	D6	D5	D4	D3	D2	D1
OUT8	OUT7	OUT6	OUT5	OUT4	OUT3	OUT2	OUT1

During a read operation, when LATCH is high, the microcontroller sends out the serial clock and shifts the internal fault indicator registers out. On each falling edge of SCLK, the device shifts out the 16-bit data from the internal register to SDO.



48-V 8-Ch Smart Low-side Driver Array

During a serial write with two devices in serial, above timing depicts serial interface configuration.



F16	F15	F14	F13	F12	F11	F10	F9
OUT8 OCP	OUT7 OCP	OUT6 OCP	OUT5 OCP	OUT4 OCP	OUT3 OCP	OUT2 OCP	OUT1 OCP
F8	F7	F6	F5	F4	F3	F2	F1
OUT8 OL	OUT7 OL	OUT6 OL	OUT5 OL	OUT4 OL	OUT3 OL	OUT2 OL	OUT1 OL

Output Driver

The device features an array of 8 low-side drivers, each consisting of a low-side MOSFET and a high-side recirculation diode. Each channel is capable of handling a maximum current of 1.5 A, although the total device current should also consider thermal effects. The drivers can accommodate both inductive and resistive loads.

When a channel is turned on, the low-side MOSFET conducts, allowing current to flow from the external load through the low-side MOSFET to the device ground. When the channel is turned off, the inductive current will continue to flow, but it will be recirculated through the internal diode to the VM pin.

It is crucial to ensure that the VM pin can handle the inductive energy. To protect against overvoltage, we recommend using an external clamp diode connected to the VM pin. The other side of the external clamp diode can be connected to either the VM or GND, depending on the specific application requirements.

Output Control by Serial Interface

Each channel of the device can be individually enabled or disabled. This can be achieved through the serial interface. When Dx is set to 1, the corresponding channel is turned on, and when it is set to 0, the channel is turned off.

Open-Load Diagnostics

During the off time of each channel, the TPM8860 can detect open loads. This is done by applying a small current of 30 μ A to the OUTx pin and comparing the voltage at OUTx with an internal threshold called Vth_open. If the output is open (no load connected), the small current will pull down the voltage at OUTx to ground, triggering the open comparator.

It's important to note that an open load condition will not prevent the channel from turning on.

If any of the channels trigger an open load fault, the nFAULT pin will be pulled low, indicating the occurrence of a fault.

Short & Over Current Protection

Each channel of the device is equipped with a short-circuit protection circuit to limit the output current and shut down the channel if an overcurrent fault is detected. If an output channel is shorted to the supply, the output current will be internally clamped to protect the channel.

During the on-time of the channel, it continuously monitors the output current. If the current exceeds a predefined threshold for a duration longer than the deglitch timer, an overcurrent fault is triggered. By default, the overcurrent protection is set to latch off. In the event of an OCP fault on any channel, the nFAULT pin will be pulled low to indicate the fault condition. The overcurrent protection is latched off. To clear the overcurrent fault, the user can use a serial interface to turn off the channel. If the current exceeds the short protection threshold, the current will be clamped at the short protection threshold.

Open-drain Fault

The TPM8860 features an open-drain output called nFAULT. This output is used to indicate the occurrence of a fault. When a fault condition occurs, the nFAULT pin is pulled down, signaling the fault status to the external circuitry.

Thermal Protection

The TPM8860 device includes thermal protection to prevent damage from excessive temperatures. When the junction temperature surpasses over temperature threshold, the thermal shutdown feature is triggered, turning off all output channels. Once the temperature drops below the threshold with hysteresis, normal operation resumes. Thermal protection ensures safe operation by monitoring and reacting to high temperatures.

Application and Implementation

Note

Information in the following application sections is not part of the 3PEAK's component specification and 3PEAK does not warrant its accuracy or completeness. 3PEAK's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

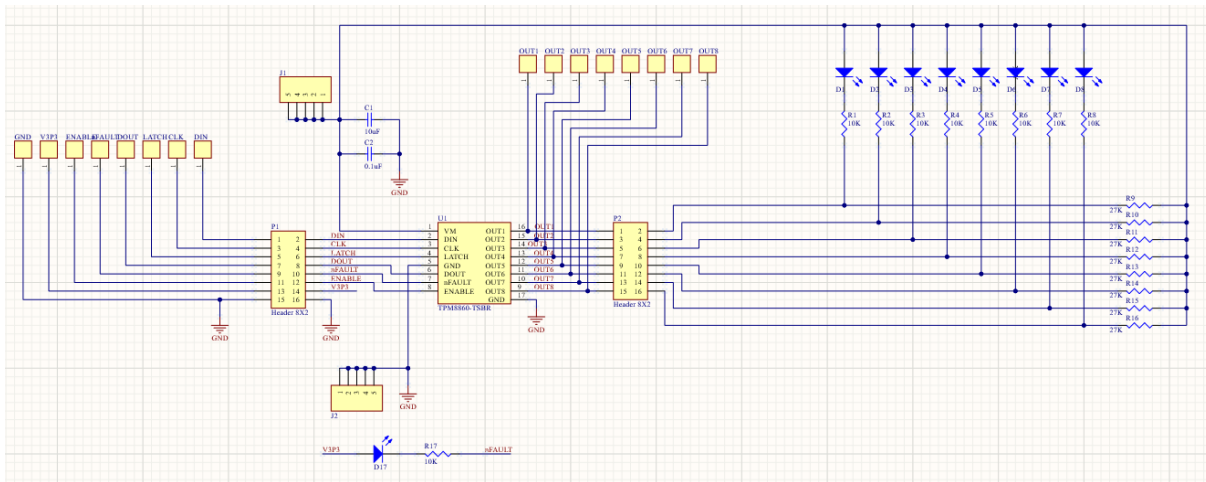
Application Information

PLC Digital Output

Serial Communication

The TPM8860 is designed for digital output control in appliance and industrial applications. It features an SPI communication interface provide reliable output control.

In industrial and appliances applications, digital outputs are commonly used to control various external devices such as motors, valves, lights, etc. The TPM8860 offers an 8-channel low-side driver array, with each channel capable of independent switching control. Through the SPI interface, the main controller can send commands to TPM8860 to control the on/off state of each channel.



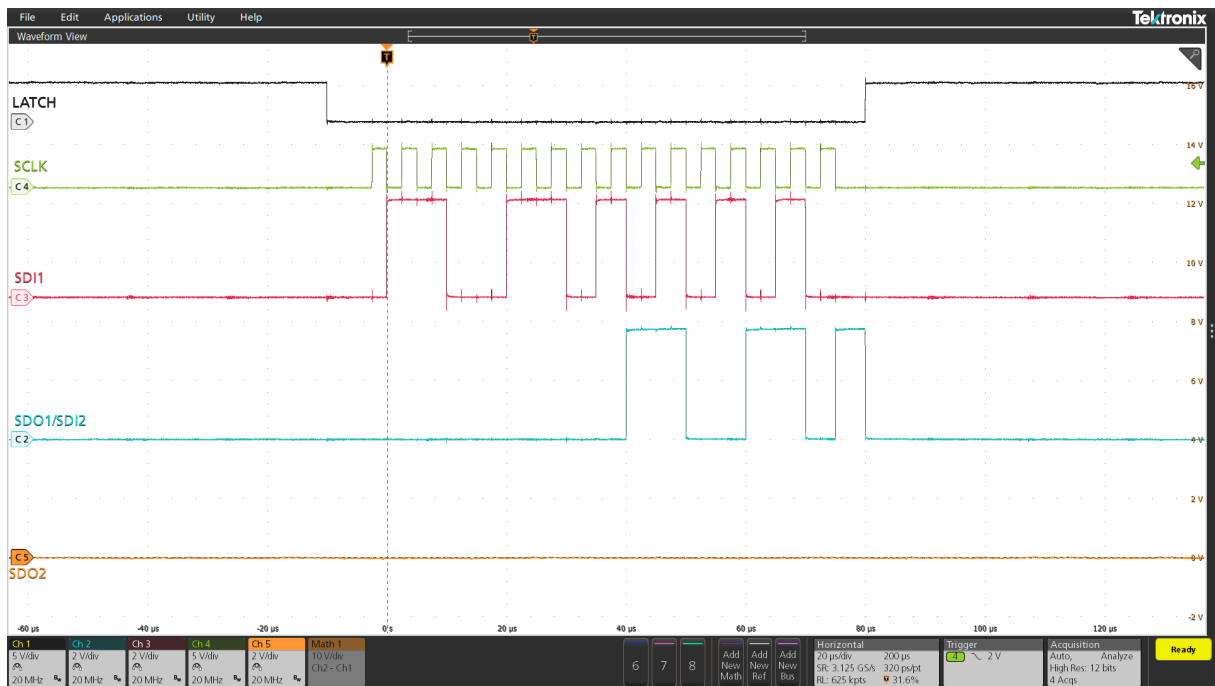


Figure 16. Serial Communication Write with DaisyChain

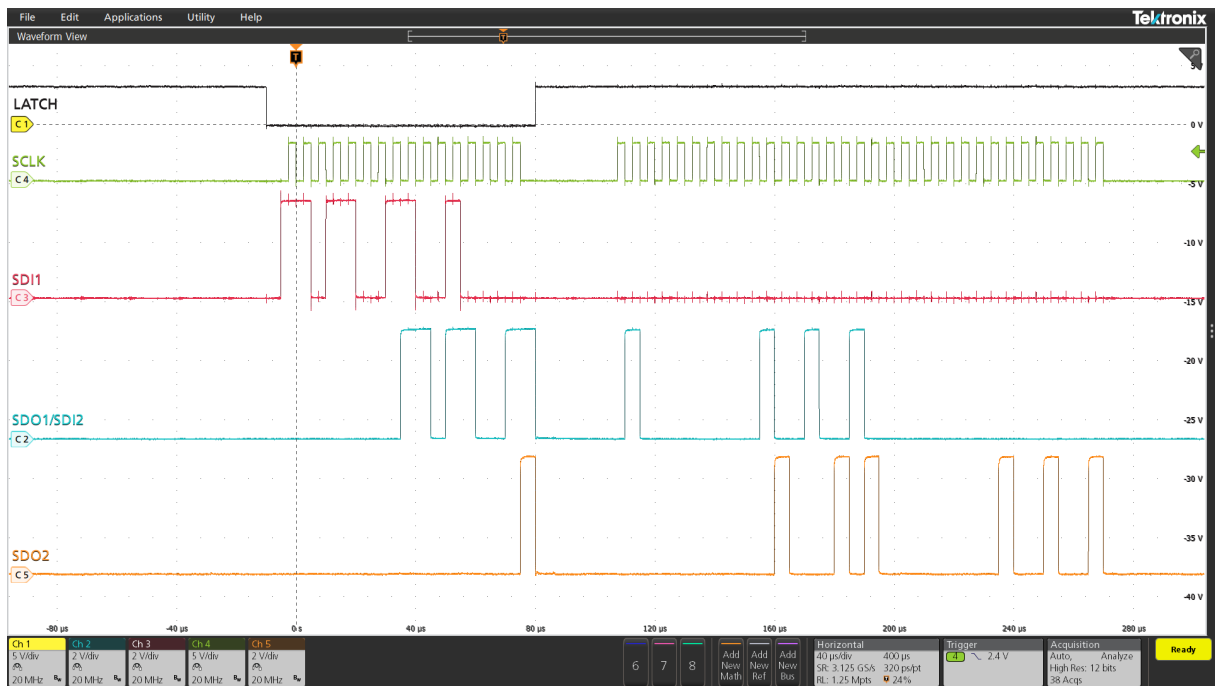


Figure 17. Serial Communication Read with DaisyChain

Typical Application

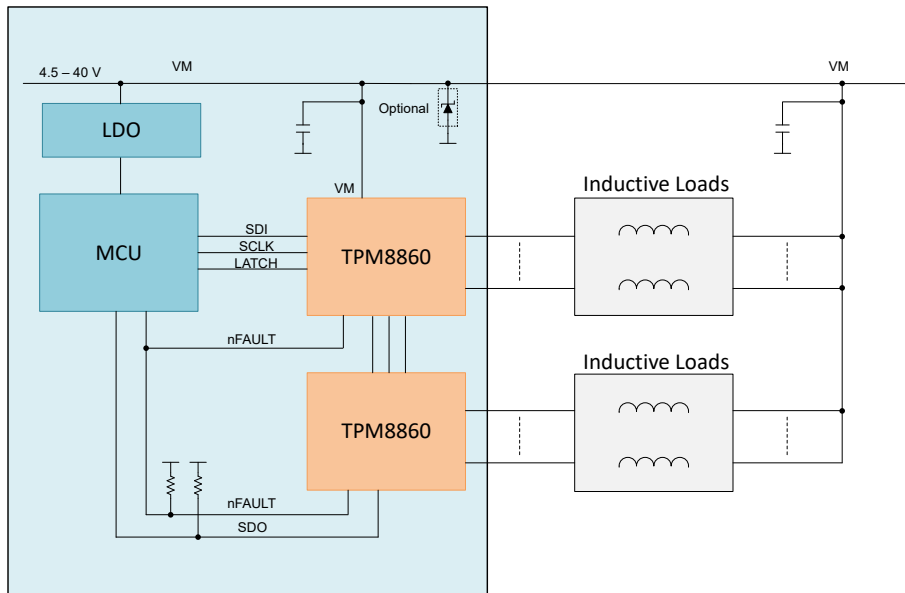


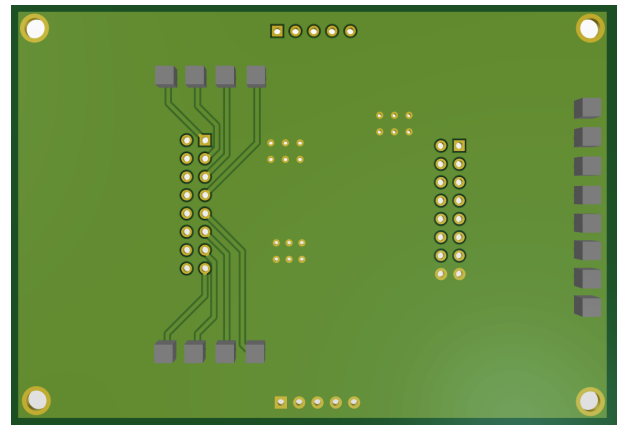
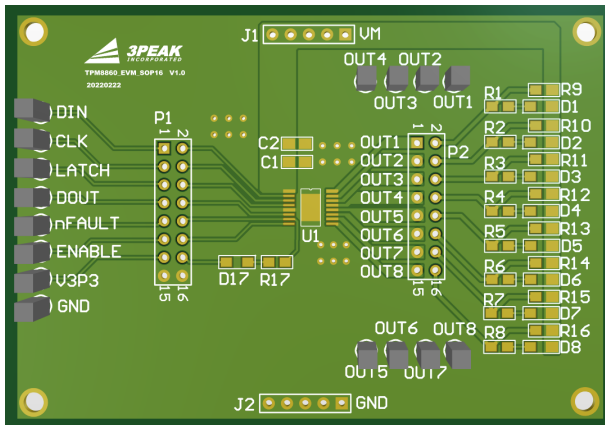
Figure 18. Typical Application Circuit

Layout

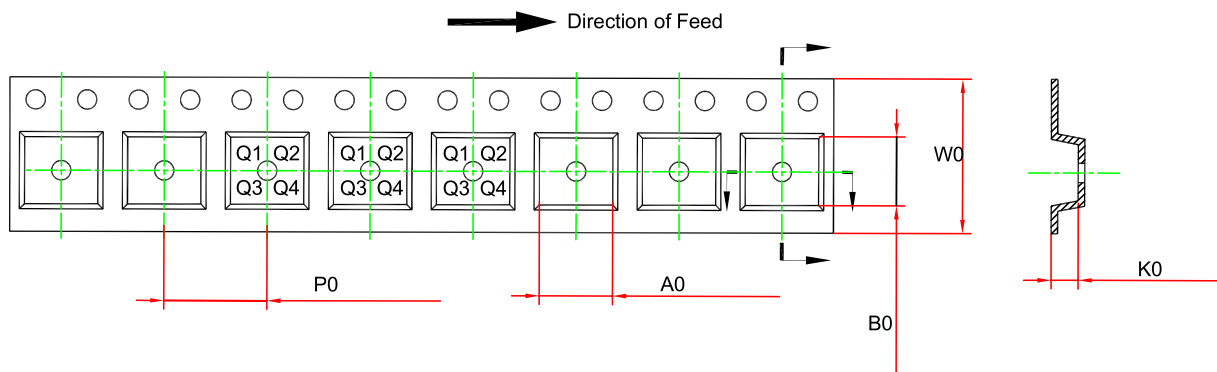
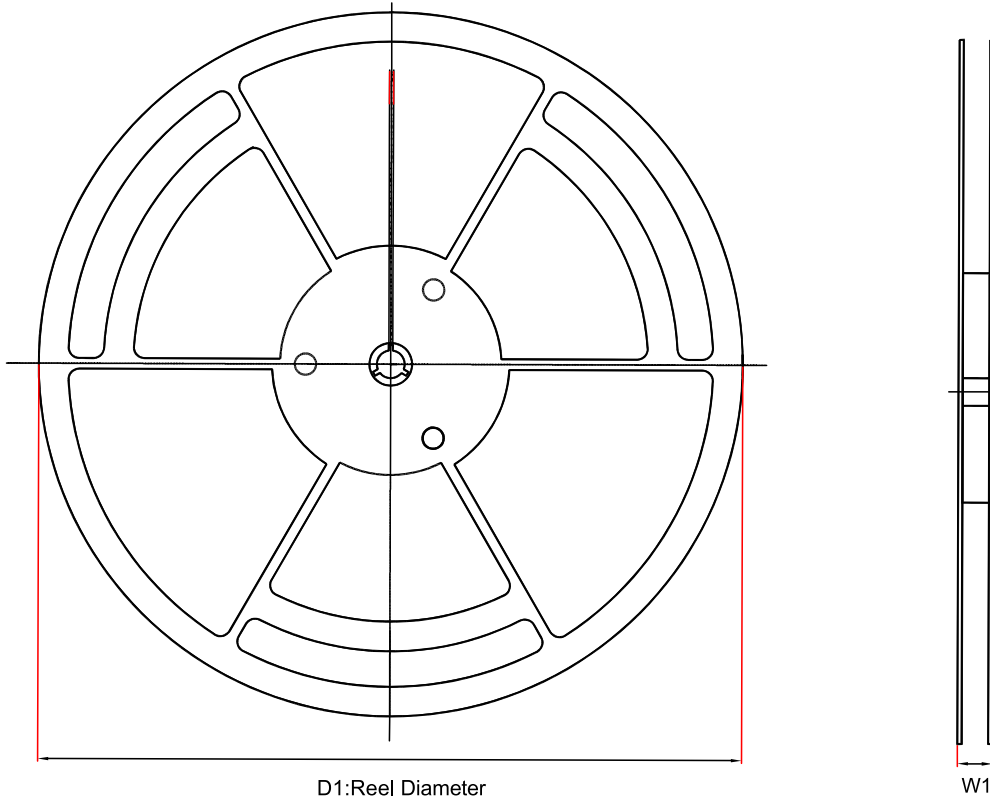
Layout Guideline

- Both input capacitors and output capacitors must be placed to the device pins as close as possible.
- It is recommended to bypass the input pin to ground with a 0.1- μ F bypass capacitor.
- It is recommended to use wide and thick copper to minimize I \times R drop and heat dissipation.
- Exposed pad must be connected to the PCB ground plane directly, the copper area must be as large as possible.

Layout Example



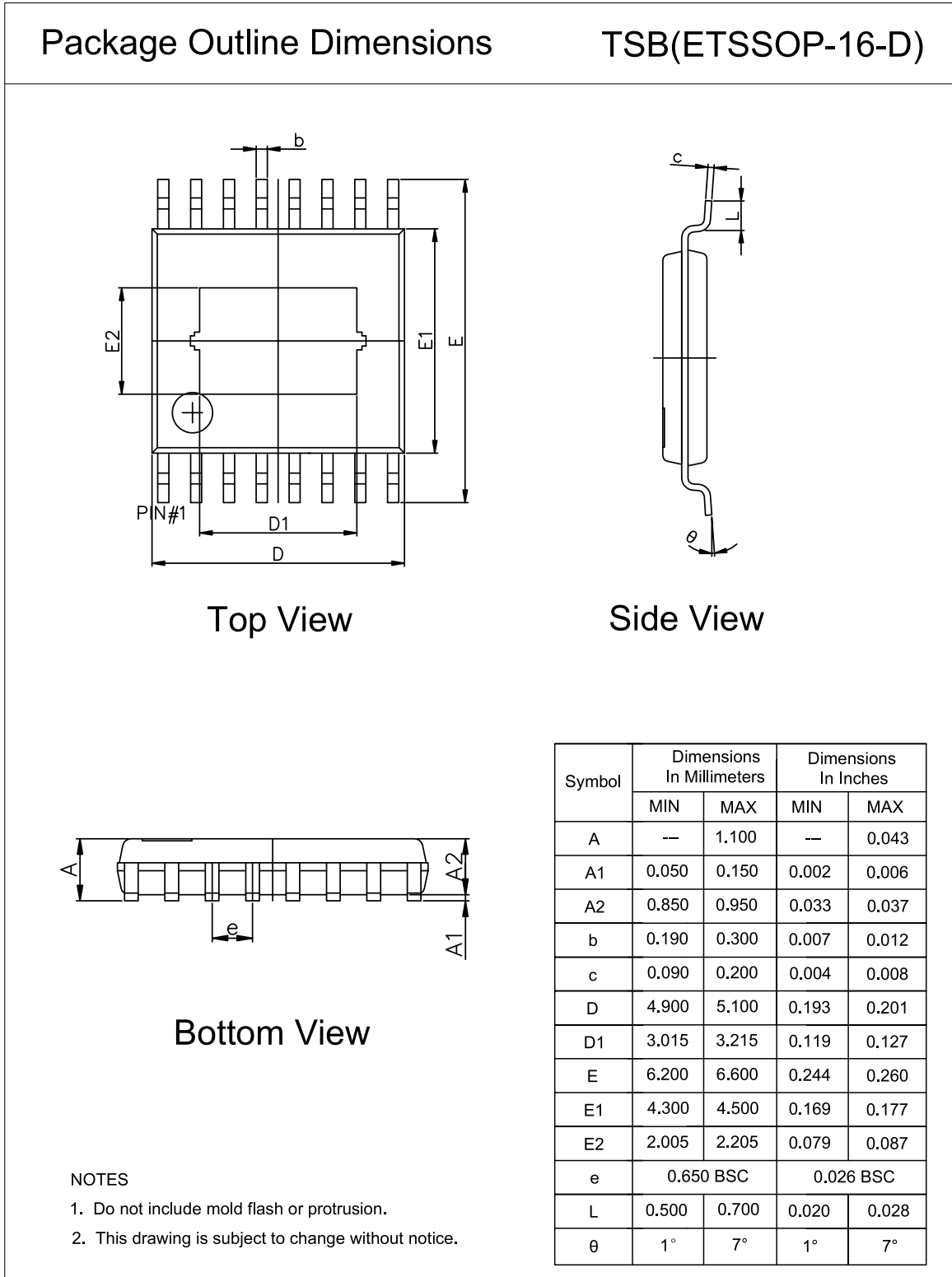
Tape and Reel Information



Order Number	Package	D1 (mm)	W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	W0 (mm)	Pin1 Quadrant
TPM8860-TSBR	ETSSOP-16	330	17.6	6.8	5.4	1.5	8	12	Q1

Package Outline Dimensions

ETSSOP-16-D



Order Information

Order Number	Operating Temperature Range	Package	Marking Information	MSL	Transport Media, Quantity	Eco Plan
TPM8860-TSBR	-40 to 125°C	ETSSOP-16	M8860	MSL3	Tape and Reel,3000	Green

Green: 3PEAK defines "Green" to mean RoHS compatible and free of halogen substances.

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